

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A ~~substrate with a microstructure semiconductor device formed thereon, the substrate comprising:~~ semiconductor device formed thereon, the substrate comprising:

~~a lower substrate supporting an upper substrate;~~

~~a buffer layer having a plurality of spaced apart shapes formed on, and extending above, a planar upper surface of the of a lower substrate; to have a plurality of shapes with air gaps defined between each of said shapes and spaced apart from each other at regular intervals; and~~

~~an adhesive layer formed directly on the plurality of spaced apart shapes; and~~

~~an upper substrate removably adhered to an upper surface of the adhesive layer; between the upper substrate and the buffer layer so that the upper substrate is removably adhered to the lower substrate by the adhesive layer and the buffer layer;~~

~~wherein, the upper substrate has a substantially higher flexibility than that of the lower substrate, and on which a semiconductor device is formed.~~

2. (Currently Amended) The ~~substrate device~~ as claimed in claim 1, wherein the lower substrate is made of at least one of Si, SiO.sub.2, Al.sub.2O.sub.3, copper, copper alloy, aluminum, aluminum alloy, and glass.

3. (Currently Amended) The ~~substrate device~~ as claimed in claim 1, wherein the buffer layer is made of at least one of SiO.sub.2, Al.sub.2O.sub.3, AlON, SiON, Si.sub.3N.sub.4, AlN, SOG (spin-on-glass), photosensitive material, Cu, Cu alloy, Al, and Al alloy.

4. (Currently Amended) The ~~substrate device~~ as claimed in claim 1, wherein the buffer layer is patterned and etched to form a plurality of shapes arranged in many rows or to form a plurality of shapes arranged in hexahedron or cylindrical islands, with stress relaxing non-enclosed air gaps being spaced apart from each other at regular intervals.

5. (Currently Amended) The ~~substrate device~~ as claimed in claim 1, wherein the adhesive layer is made of any one of a double sided tape, a liquid adhesive, and organic film, to withstand a hot process of more than 100.degree. C.

6. (Currently Amended) The ~~substrate device~~ as claimed in claim 1, wherein the upper substrate is made of any one of plastic, stainless steel, copper, copper alloy, aluminum, aluminum alloy, silicon, and glass.

7-14. (Canceled).